



CYPRESS

CY7C385A CY7C386A

Very High Speed 4K (12K) Gate CMOS FPGA

Features

- **Very high speed**
 - Loadable counter frequencies greater than 100 MHz
 - Chip-to-chip operating frequencies up to 85 MHz
 - Input + logic cell + output delays under 7 ns
- **Unparalleled FPGA performance** for counters, data path, state machines, arithmetic, and random logic
- **High usable density**
 - 16 x 24 array of 384 logic cells provides 12,000 total available gates
 - 4,000 typically usable "gate array" gates in 84-pin PLCC/CLCC, 100-pin and 144-pin TQFP, 145-pin CPGA, and 160-pin CQFP packages
- **Low power, high output drive**
 - Standby current typically 2 mA
 - 16-bit counter operating at 100 MHz consumes 50 mA
 - Minimum I_{OL} and I_{OH} of 8 mA
- **Flexible logic cell architecture**
 - Wide fan-in (up to 14 input gates)
 - Multiple outputs in each cell
 - Very low cell propagation delay (1.7 ns)
- **Powerful design tools—Warp3™**
 - Designs entered in VHDL, schematics, or both

- Fast, fully automatic place and route
- Waveform simulation with back annotated net delays
- PC and workstation platforms
- **Robust routing resources**
 - Fully automatic place and route of designs using up to 100 percent of logic resources
 - No hand routing required
- 88 (7C385A) to 122 (7C386A) bidirectional input/output pins
- 6 dedicated input/high-drive pins
- 2 clock/dedicated input pins with fan-out-independent, low-skew nets
 - Clock skew < 1 ns
- **Input hysteresis provides high noise immunity**
- **Thorough testability**
 - Built-in scan path permits 100 percent factory testing of logic and I/O cells
 - Automatic Test Vector Generation (ATVG) software supports user testing after programming
- 0.65μ CMOS process with ViaLink™ programming technology
 - High-speed metal-to-metal link
 - Non-volatile antifuse technology
- 100-pin TQFP is pin compatible with the 1K (CY7C381A/2A) and the 2K (CY7C383A/4A) FPGAs

Functional Description

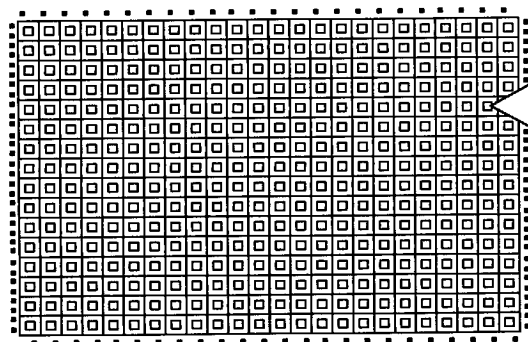
The CY7C385A and CY7C386A are very high speed CMOS user-programmable ASIC (pASIC™) devices. The 384 logic cell field-programmable gate array (FPGA) offers 4,000 typically usable "gate array" gates. This is equivalent to 12,000 EPLD or LCA gates. The CY7C385A is available in a 84-pin PLCC and CPGA and the 100-pin TQFP. The CY7C386A is available in 144-pin TQFP and CPGA packages, and a 160-pin CQFP package.

Low-impedance, metal-to-metal ViaLink interconnect technology provides non-volatile custom logic capable of operating at speeds above 150 MHz with input and output delays under 3 ns. This permits high-density programmable devices to be used with today's fastest CISC and RISC microprocessors.

Designs are entered into the CY7C385A and CY7C386A using Cypress Warp3 software or one of several third-party tools. Warp3 is a sophisticated CAE package that features schematic entry, waveform-based timing simulation, and VHDL design synthesis. The CY7C385A and CY7C386A feature ample on-chip routing channels for fast, fully automatic place and route of high gate utilization designs.

For detailed information about the pASIC380 architecture, see the pASIC380 Family datasheet.

Logic Block Diagram

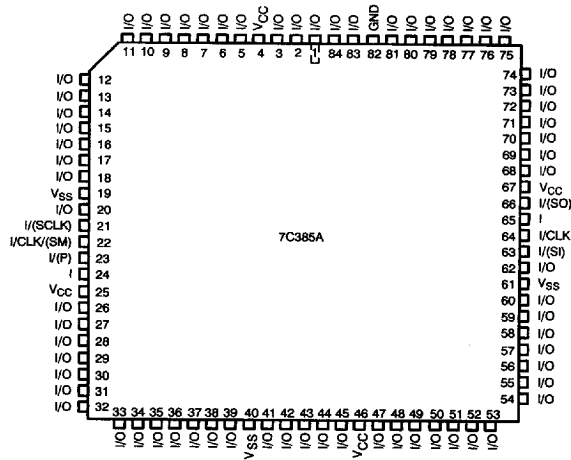
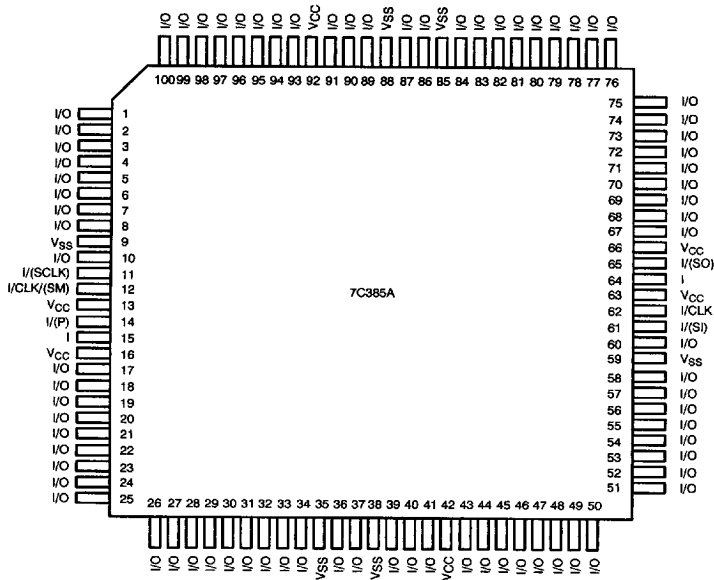


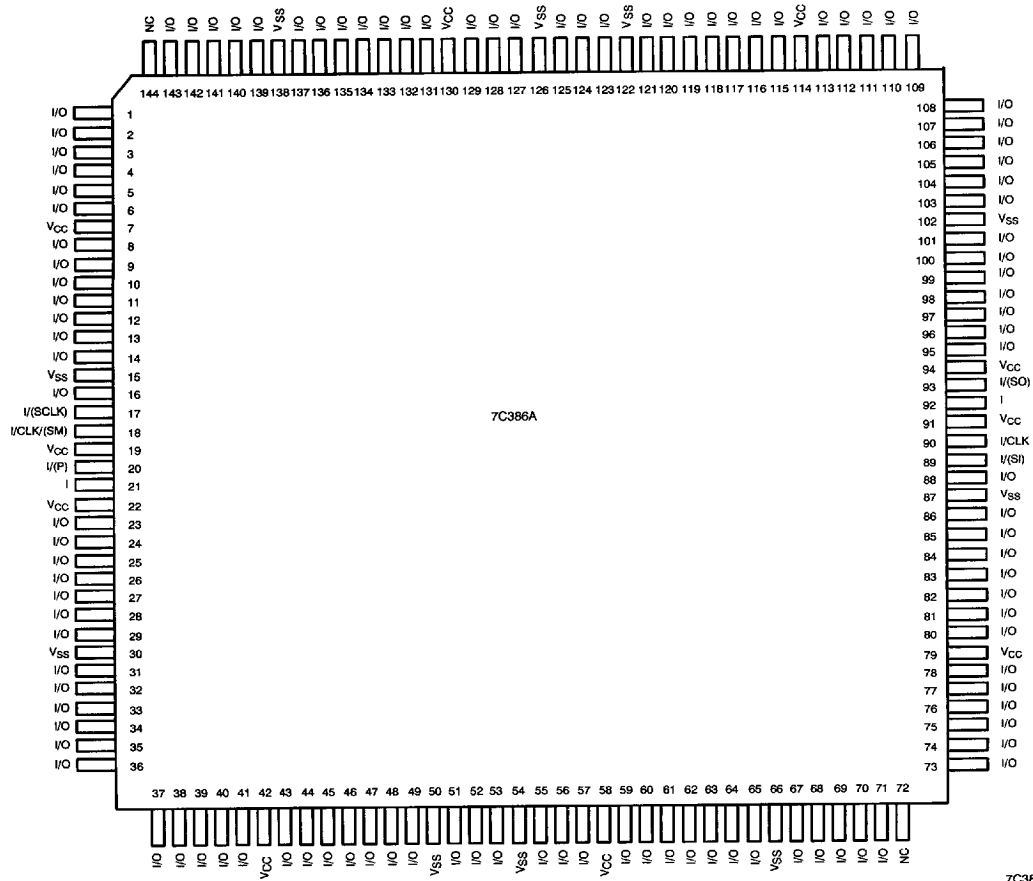
■ I/O/HIGH-DRIVE INPUT/
CLOCK CELLS

84 and 144 PINS, 114 I/O CELLS, 6 INPUT HIGH DRIVE CELLS, 2 INPUT/CLK (HIGH DRIVE) CELLS

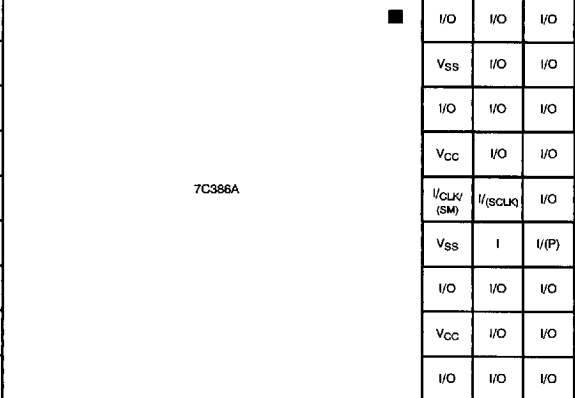
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Warp3 is a trademark of Cypress Semiconductor Corporation.

Pin Configurations
**PLCC/CLCC
Top View**

**TQFP
Top View**


Pin Configurations (continued)
TQFP
Top View


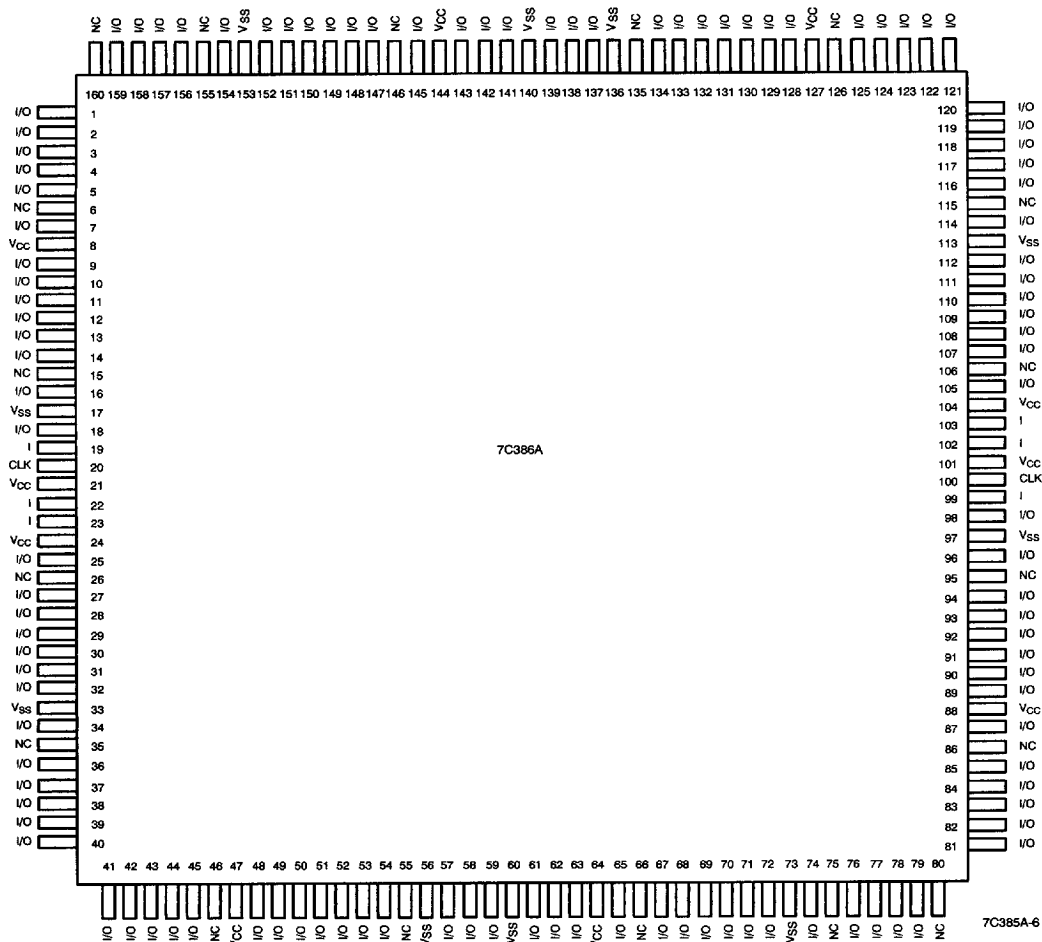
Pin Configurations (continued)
**CPGA
Bottom View**

R	P	N	M	L	K	J	H	G	F	E	D	C	B	A	
I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	1
I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	NC	I/O	2
I/O	I/O	V _{SS}	I/O	V _{CC}	I/O	V _{SS}	I/O	V _{CC}	I/O	V _{SS}	I/O	V _{CC}	I/O	I/O	3
I/O	I/O	I/O	 7C386A									I/O	I/O	I/O	4
I/O	I/O	V _{CC}										V _{SS}	I/O	I/O	5
I/O	I/O	I/O										I/O	I/O	I/O	6
I	I/(SO)	V _{SS}										V _{CC}	I/O	I/O	7
I/O	I/(SI)	I/CLK										I/CLK (SM)	I/(SCLK)	I/O	8
I/O	I/O	V _{CC}										V _{SS}	I	I/(P)	9
I/O	I/O	I/O										I/O	I/O	I/O	10
I/O	I/O	V _{SS}										V _{CC}	I/O	I/O	11
I/O	I/O	I/O										I/O	I/O	I/O	12
I/O	I/O	V _{CC}	I/O	V _{SS}	I/O	V _{CC}	I/O	V _{SS}	I/O	V _{CC}	I/O	V _{SS}	I/O	I/O	13
I/O	NC	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	14
I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	15

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Pin Configurations (continued)

QFP
Top View



Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature	
Ceramic	-65°C to +150°C
Plastic	-40°C to +125°C
Lead Temperature	300°C
Supply Voltage	-0.5V to +7.0V
Input Voltage	-0.5V to $V_{CC} + 0.5V$
ESD Pad Protection	$\pm 2000\text{ V}$
DC Input Voltage	-0.5V to 7.0V

Latch-Up Current $\pm 200\text{ mA}$

Operating Range

Range	Ambient Temperature	V_{CC}
Commercial	0°C to +70°C	5V $\pm 5\%$
Industrial	-40°C to +85°C	5V $\pm 10\%$
Military	-55°C to +125°C	5V $\pm 10\%$

Delay Factor (K)

Speed Grade	Military		Industrial		Commercial	
	Min.	Max.	Min.	Max.	Min.	Max.
-0	0.39	1.82	0.4	1.67	0.46	1.55
-1	0.39	1.56	0.4	1.43	0.46	1.33
-2			0.4	1.35	0.46	1.25

Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions	Min.	Max.	Unit
V_{OH}	Output HIGH Voltage	$I_{OH} = -4.0\text{ mA}$	3.7		V
		$I_{OH} = -8.0\text{ mA}$	2.4		V
		$I_{OH} = -10.0\text{ }\mu\text{A}$	$V_{CC} - 0.1$		V
V_{OL}	Output LOW Voltage	$I_{OL} = 8.0\text{ mA}$ Military/Industrial		0.4	V
		$I_{OL} = 12\text{ mA}$ Commercial			V
		$I_{OL} = 10.0\text{ }\mu\text{A}$		0.1	V
V_{IH}	Input HIGH Voltage		2.0		V
V_{IL}	Input LOW Voltage			0.8	V
I_I	Input Leakage Current	$V_{IN} = V_{CC}$ or V_{SS}	-10	+10	μA
I_{OZ}	Three-State Output Leakage Current	$V_{IN} = V_{CC}$ or V_{SS}	-10	+10	μA
I_{OS}	Output Short Circuit Current	$V_{OUT} = V_{SS}$	-10	-80	mA
		$V_{OUT} = V_{CC}$	30	140	mA
I_{CC}	Standby Supply Current	$V_{IN}, V_{IO} = V_{CC}$ or V_{SS}		10	mA

Capacitance

Parameter	Description	Test Conditions	Max.	Unit
C_{IN}	Input Capacitance ^[1]	$T_A = 25^\circ\text{C}, f = 1\text{ MHz},$ $V_{CC} = 5.0\text{V}$	10	pF
C_{OUT}	Output Capacitance		20	pF

Notes:

1. $C_I = 45\text{ pF}$ max. on I(SI) and I(P).

Switching Characteristics Over the Operating Range

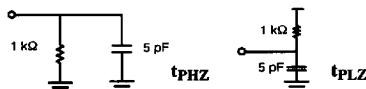
Parameter	Description	Propagation Delays ^[2] with Fanout of					Unit
		1	2	3	4	8	
LOGIC CELLS							
t _{PD}	Combinatorial Delay ^[3]	1.7	2.2	2.6	3.2	5.3	ns
t _{SU}	Set-Up Time ^[3]	2.1	2.1	2.1	2.1	2.1	ns
t _H	Hold Time	0.0	0.0	0.0	0.0	0.0	ns
t _{CLK}	Clock to Q Delay	1.0	1.5	1.9	2.6	4.7	ns
t _{CWHI}	Clock HIGH Time	2.0	2.0	2.0	2.0	2.0	ns
t _{CWLO}	Clock LOW Time	2.0	2.0	2.0	2.0	2.0	ns
t _{SET}	Set Delay	1.7	2.2	2.6	3.2	5.3	ns
t _{RESET}	Reset Delay	1.5	1.9	2.2	2.7	4.4	ns
t _{SW}	Set Width	1.9	1.9	1.9	1.9	1.9	ns
t _{RW}	Reset Width	1.8	1.8	1.8	1.8	1.8	ns

Parameter	Description	Propagation Delays ^[2]						Unit
		1	2	3	4	8	12	
INPUT CELLS								
t _{IN}	Input Delay (HIGH Drive)	2.8	2.9	3.0	3.1	4.0	5.3	ns
t _{NI}	Input, Inverting Delay (HIGH Drive)	3.0	3.1	3.2	3.3	4.1	5.7	ns
t _{IO}	Input Delay (Bidirectional Pad)	1.4	1.9	2.2	2.2	4.7	6.5	ns
t _{GCK}	Clock Buffer Delay ^[4]	2.7	2.8	2.9	3.0	3.1	3.3	ns
t _{GCKHI}	Clock Buffer Min. HIGH ^[4]	2.0	2.0	2.0	2.0	2.0	2.0	ns
t _{GCKLO}	Clock Buffer Min. LOW ^[4]	2.0	2.0	2.0	2.0	2.0	2.0	ns

Parameter	Description	Propagation Delays ^[2] with Output Load Capacitance (pF) of					Unit
		30	50	75	100	150	
OUTPUT CELLS							
t _{OUTLH}	Output Delay LOW to HIGH	2.7	3.4	4.2	5.0	6.7	ns
t _{OUTHL}	Output Delay HIGH to LOW	2.8	3.7	4.7	5.6	7.6	ns
t _{PZH}	Output Delay Three-State to HIGH	4.0	4.9	6.1	7.3	9.7	ns
t _{PZL}	Output Delay Three-State to LOW	3.6	4.2	5.0	5.8	7.3	ns
t _{PHZ}	Output Delay HIGH to Three-State ^[5]	2.9					ns
t _{PLZ}	Output Delay LOW to Three-State ^[5]	3.3					ns

Notes:

- Worst-case propagation delay times over process variation at V_{CC} = 5.0V and T_A = 25°C. Multiply by the appropriate delay factor, K_d, for speed grade to get worst-case parameters over full V_{CC} and temperature range as specified in the operating range. All inputs are TTL with 3-ns linear transition time between 0 and 3 volts.
- These limits are derived from worst-case values for a representative selection of the slowest paths through the pASIC logic cell including net delays. Guaranteed delay values for specific paths should be determined from simulation results.
- Clock buffer fanout refers to the maximum number of flip-flops per half column. The number of half columns used does not affect clock buffer delay.
- The following loads are used for t_{PHZ}:

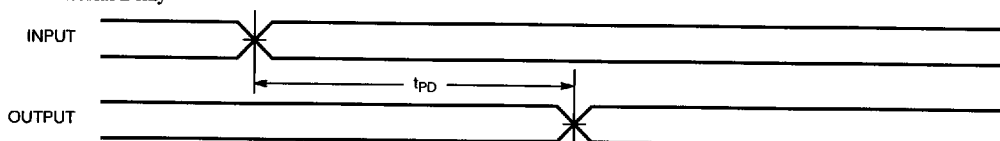


High Drive Buffer

Parameter	Description	# High Drives Wired Together	Propagation Delays ^[2] with Fanout of					Unit
			12	24	48	72	96	
t_{IN}	High Drive Input Delay	1	5.3	6.7				ns
		2		4.5	6.6			ns
		3			5.3	6.2	7.2	ns
		4				5.4	6.2	ns
t_{INI}	High Drive Input, Inverting Delay	1	5.7	7.2				ns
		2		4.6	6.8			ns
		3			5.5	6.4	7.4	ns
		4				5.6	6.4	ns

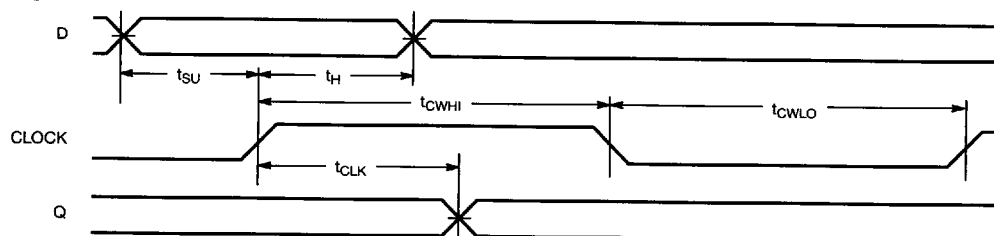
Switching Waveforms

Combinatorial Delay



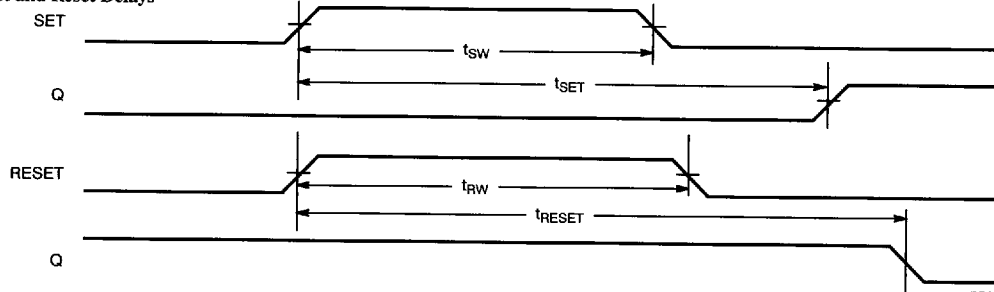
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Set-Up and Hold Times



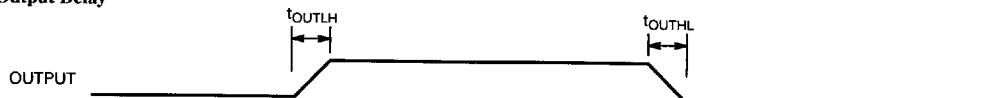
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Set and Reset Delays



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Output Delay



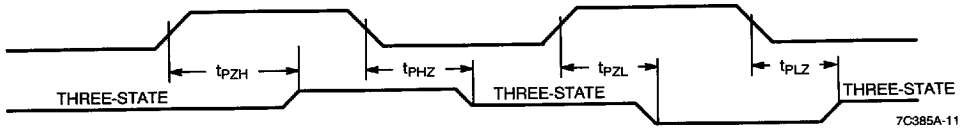
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Switching Waveforms (continued)

Three-State Delay

OUTPUT
BUFFER
ENABLE

OUTPUT

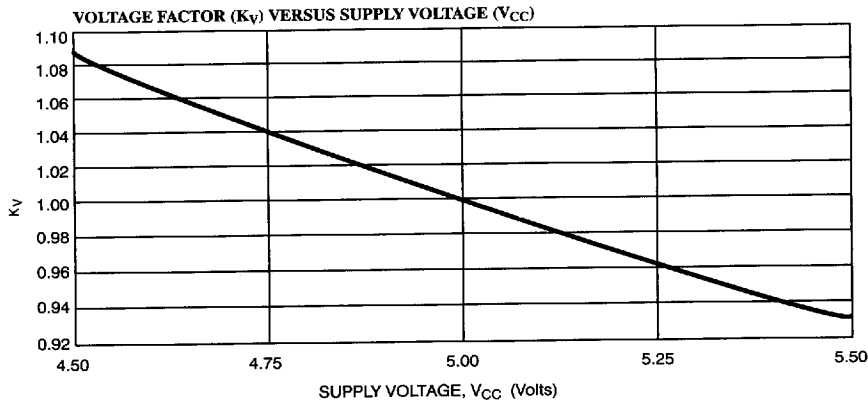


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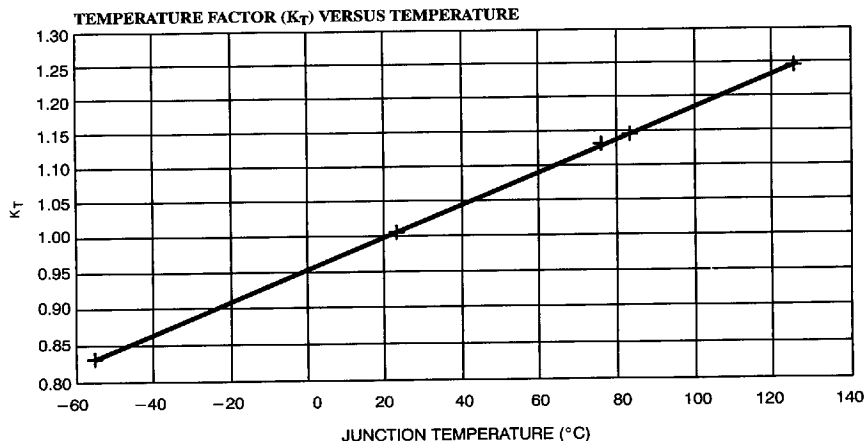
Typical AC Characteristics

Propagation delays depend on routing, fanout, load capacitance, supply voltage, junction temperature, and process variation. The AC Characteristics are a design guide to provide initial timing estimates at nominal conditions. Worst-case estimates are obtained when nominal propagation delays are multiplied by the appropriate Delay Factor, K, as specified by the speed grade in the Delay

Factor table. The effects of voltage and temperature variation are illustrated in the graphs below. *Warp3* incorporates datasheet AC Characteristics into the design database for pre-place-and-route simulations. The *Warp3* Delay Modeler extracts specific timing parameters for precise simulation results following place and route.

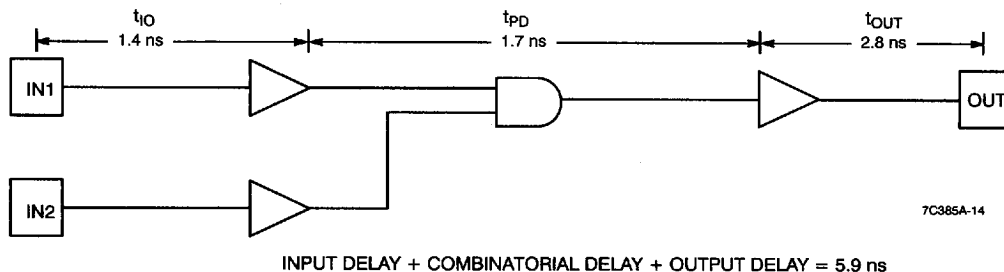
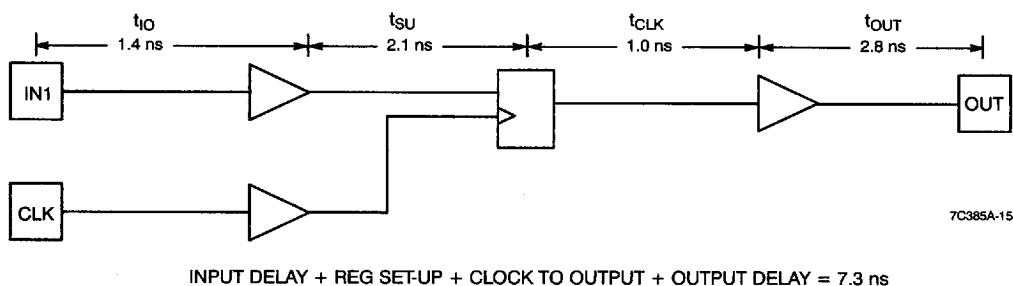


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* $\theta_{JA} = 45^{\circ}\text{C/WATT}$ FOR PLCC

Combinatorial Delay Example (Load = 30 pF)

Sequential Delay Example (Load = 30 pF)

Ordering Information

Speed Grade	Ordering Code	Package Name	Package Type	Operating Range
2	CY7C385A-2AC	A100	100-Pin Thin Quad Flat Pack	Commercial
	CY7C385A-2JC	J83	84-Lead Plastic Leaded Chip Carrier	
	CY7C385A-2AI	A100	100-Pin Thin Quad Flat Pack	Industrial
	CY7C385A-2JI	J83	84-Lead Plastic Leaded Chip Carrier	
1	CY7C385A-1AC	A100	100-Pin Thin Quad Flat Pack	Commercial
	CY7C385A-1JC	J83	84-Lead Plastic Leaded Chip Carrier	
	CY7C385A-1AI	A100	100-Pin Thin Quad Flat Pack	Industrial
	CY7C385A-1JI	J83	84-Lead Plastic Leaded Chip Carrier	
0	CY7C385A-0AC	A100	100-Pin Thin Quad Flat Pack	Commercial
	CY7C385A-0JC	J83	84-Lead Plastic Leaded Chip Carrier	
	CY7C385A-0AI	A100	100-Pin Thin Quad Flat Pack	Industrial
	CY7C385A-0JI	J83	84-Lead Plastic Leaded Chip Carrier	

Ordering Information (continued)

Speed Grade	Ordering Code	Package Name	Package Type	Operating Range
2	CY7C386A-2AC	A144	144-Pin Thin Quad Flat Pack	Commercial
	CY7C386A-2GC	G145	145-Pin Grid Array (Cavity Up)	
	CY7C386A-2UC	U162	160-Lead Ceramic Quad Flatpack (Cavity Up)	
	CY7C386A-2AI	A144	144-Pin Thin Quad Flat Pack	Industrial
	CY7C386A-2GI	G145	145-Pin Grid Array (Cavity Up)	
	CY7C386A-2UI	U162	160-Lead Ceramic Quad Flatpack (Cavity Up)	
1	CY7C386A-1AC	A144	144-Pin Thin Quad Flat Pack	Commercial
	CY7C386A-1GC	G145	145-Pin Grid Array (Cavity Up)	
	CY7C386A-1UC	U162	160-Lead Ceramic Quad Flatpack (Cavity Up)	
	CY7C386A-1AI	A144	144-Pin Thin Quad Flat Pack	Industrial
	CY7C386A-1GI	G145	145-Pin Grid Array (Cavity Up)	
	CY7C386A-1UI	U162	160-Lead Ceramic Quad Flatpack (Cavity Up)	
	CY7C386A-1GMB	G145	145-Pin Grid Array (Cavity Up)	Military
	CY7C386A-1UMB	U162	160-Lead Ceramic Quad Flatpack (Cavity Up)	
0	CY7C386A-0AC	A144	144-Pin Thin Quad Flat Pack	Commercial
	CY7C386A-0GC	G145	145-Pin Grid Array (Cavity Up)	
	CY7C386A-0UC	U162	160-Lead Ceramic Quad Flatpack (Cavity Up)	
	CY7C386A-0AI	A144	144-Pin Thin Quad Flat Pack	Industrial
	CY7C386A-0GI	G145	145-Pin Grid Array (Cavity Up)	
	CY7C386A-0UI	U162	160-Lead Ceramic Quad Flatpack (Cavity Up)	
	CY7C386A-0GMB	G145	145-Pin Grid Array (Cavity Up)	Military
	CY7C386A-0UMB	U162	160-Lead Ceramic Quad Flatpack (Cavity Up)	

Shaded area contains advanced information.

Military Specifications
Group A Subgroup Testing
DC Characteristics

Parameters	Subgroups
V _{OH}	1, 2, 3
V _{OL}	1, 2, 3
I _{OZ}	1, 2, 3
I _{CC1}	1, 2, 3

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